

Engineering Specification



SC2450P3216B0

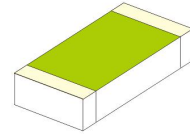
1. Product number

SC2450P3216B0

(1)(2) (3) (4) (5) (6)

Numbers Information:

- (1)Product Company: SemitelElectronics Co., Ltd.
- (2)Antenna Type: Chip Antenna
- (3)Center Frequency: 2440MHz
- (4)Feed Mode: PIFA
- (5)External Dimensions(L×W×H) (mm): 3.20*1.60*0.45
- (6)Product Series: B 0



2. Features

- Stable and reliable in performances
- Low profile, compact size
- RoHS compliance
- SMT processes compatible

3. Applications

- ISM 2.4GHz application
- ZigBee/BLE application
- Bluetooth earphone systems
- Hand-held devices when Wi-Fi / Bluetooth functions are needed, e.g., Smart phone
- IEEE802.11 b/g/n
- Wireless PCMCIA cards or USB dongles

UNLESS OTHER SPECIFIED TOLERANCES ON:

0=±1 0.0=±0.50 0.00=±0.20

ANGLES = ±

HOLE DIA = ±



Semitel Electronics Co.,Ltd

SCALE: N/A

UNIT: mm

DRAWN BY: SARA

CHECKED BY:XD

DESIGNED BY: HEXIN

APPROVED BY: XD

THIS DRAWINGS AND SPECIFICATIONS ARE THEPROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

TITLE: SC2450P3216A0Engineering Specification

DOCUMENT
NO.

SC2450P3216B0

SPEC REV.

B0

PAGE1

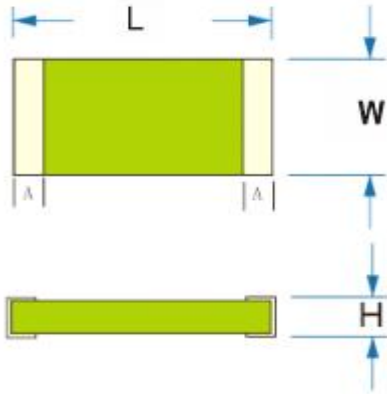
OF

9

4. Description

Semitel's chip antenna is designed for ISM 2.4GHz applications, covering frequencies 2400~2500MHz. Fabricated with proprietary design and processes, it shows excellent performance and is fully compatible with SMT processes which can decrease the assembly cost and improve device's quality and consistency.

5. Shape and Dimensions



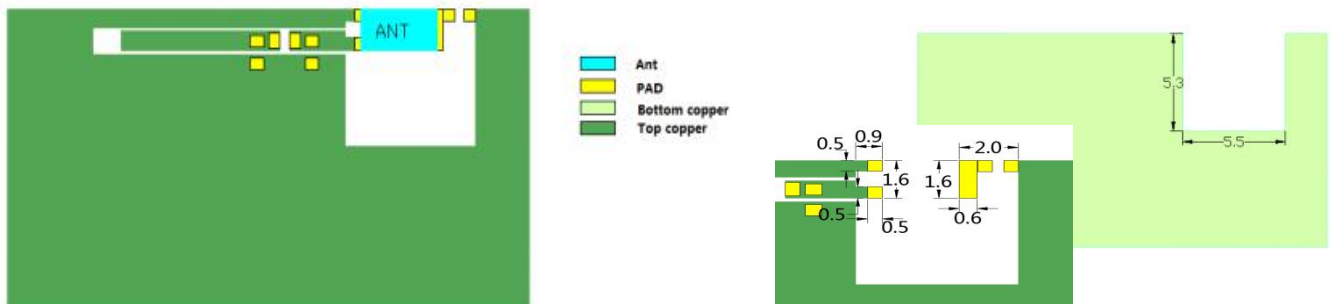
	Dimensions(mm)
L	3.20 ± 0.20
W	1.60 ± 0.20
H	0.45 ± 0.20
A	0.35 ± 0.25

6. Layout Guide & Electrical Specifications

6.1 Layout Guide (unit: mm)

Solder Land Pattern:

The solder land pattern (gold marking areas) is shown blow. Recommendation on matching circuit will be provided according to customer's installation conditions.



UNLESS OTHER SPECIFIED TOLERANCES ON:

$0 = \pm 1$ $0.0 = \pm 0.50$ $0.00 = \pm 0.20$

ANGLES = \pm HOLE DIA = \pm



Semitel Electronics Co.,Ltd

SCALE: N/A

UNIT: mm

DRAWN BY: SARA

CHECKED BY: XD

DESIGNED BY: HEXIN

APPROVED BY: XD

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

TITLE: SC2450P3216A0Engineering Specification

DOCUMENT NO.

SC2450P3216B0

SPEC REV.

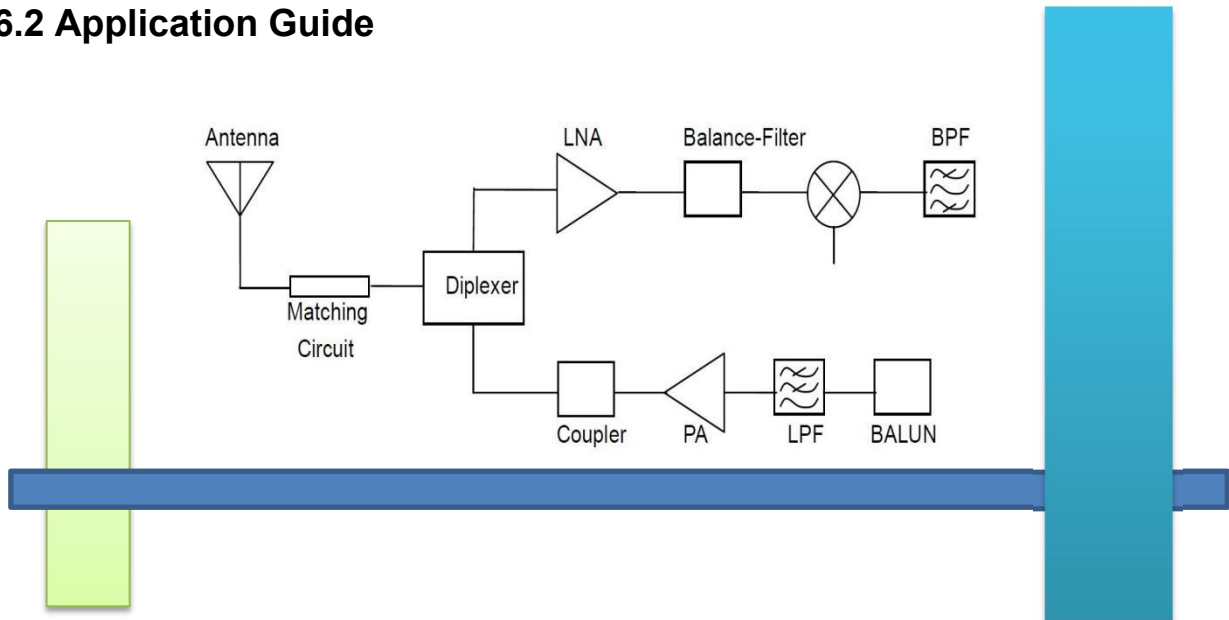
B0

PAGE2

OF

9

6.2 Application Guide



6.3 Electrical Specifications (Evaluation Board Dimensions: 86*50)

Electrical Table (2400~2500 MHz Band)

Product number	S-C-2450-P-3216-A0	
Central Frequency	2440	MHz
Bandwidth	100 (Min.)	MHz
Return Loss	-11.6 (Max.)	dB
Peak Gain	1.268	dBi
Impedance	50	Ω
Operating Temperature	-40~+85	$^{\circ}\text{C}$
Maximum Power	5	W
Resistance to soldering heat	10 (@260 $^{\circ}\text{C}$)	Sec.
Polarization	Linear	
Azimuth Beam width	Omni-directional	
Termination	Sn (leadless)	

UNLESS OTHER SPECIFIED TOLERANCES ON:

0=±1 0.0=±0.50 0.00=±0.20

ANGLES = ± HOLE DIA = ±



Semitel Electronics Co.,Ltd

SCALE: N/A

UNIT: mm

DRAWN BY: SARA

CHECKED BY: XD

DESIGNED BY: HEXIN

APPROVED BY: XD

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

TITLE: SC2450P3216A0Engineering Specification

DOCUMENT NO.

SC2450P3216B0

SPEC REV.

B0

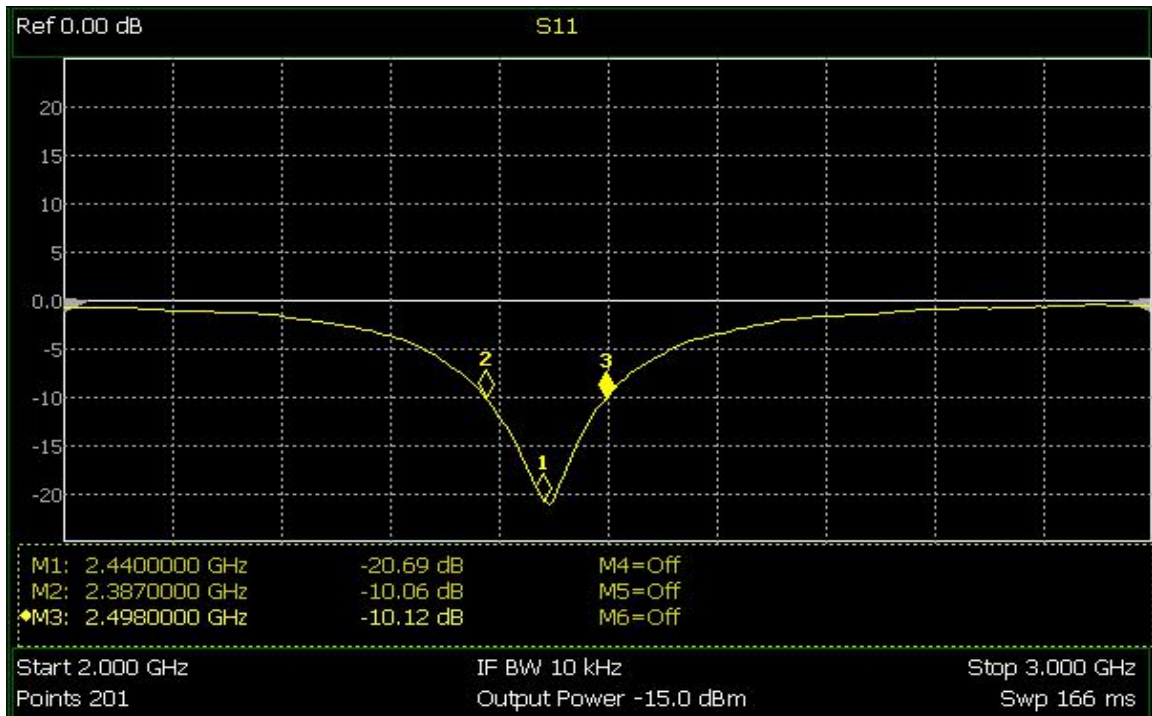
PAGE3

OF

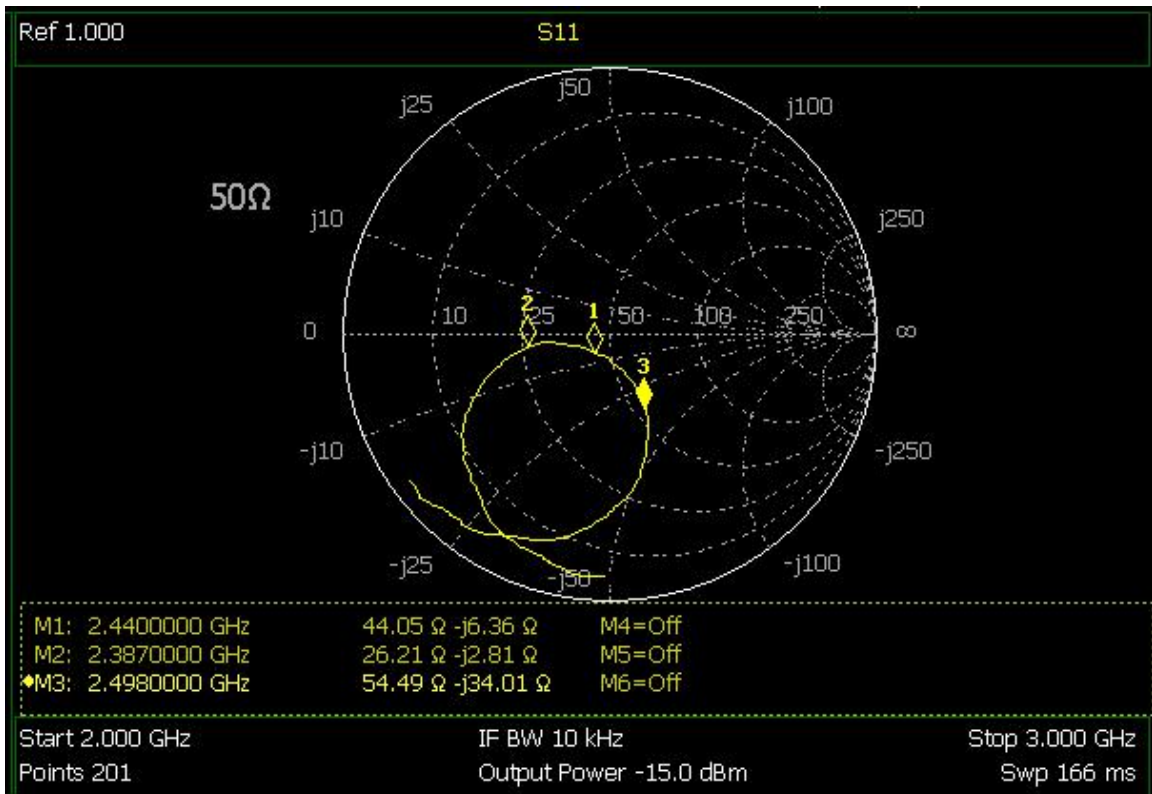
9

7. Electrical Characteristics

Return Loss



Smith Chart



UNLESS OTHER SPECIFIED TOLERANCES ON:

0= \pm 1 0.0= \pm 0.50 0.00= \pm 0.20

ANGLES = \pm HOLE DIA = \pm



Semitel Electronics Co.,Ltd

SCALE: N/A UNIT: mm
DRAWN BY: SARA CHECKED BY: XD
DESIGNED BY: HEXIN APPROVED BY: XD

THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

TITLE: SC2450P3216A0Engineering Specification

DOCUMENT NO.

SC2450P3216B0

SPEC REV.

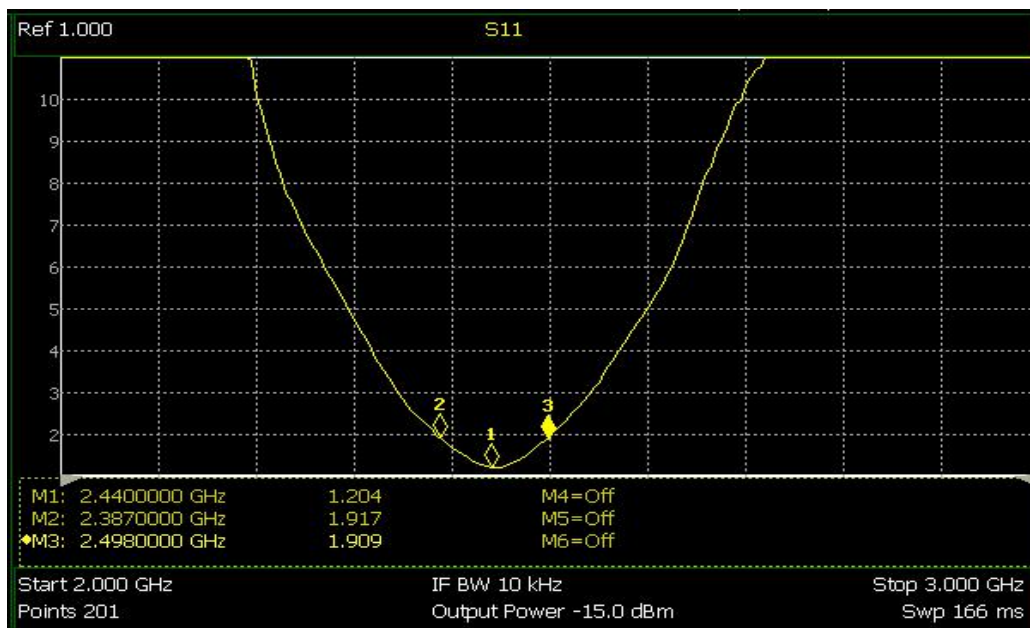
B0

PAGE4

OF

9

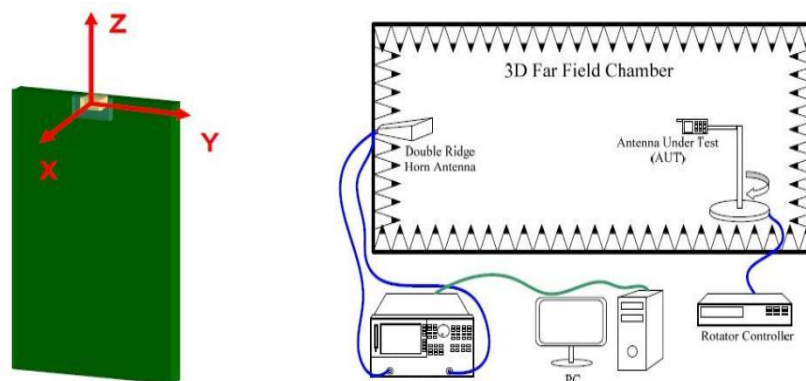
- **VSWR**




Mark	Frequency	VSWR
1	2387 MHz	1.917
2	2440 MHz	1.204
3	2498 MHz	1.909

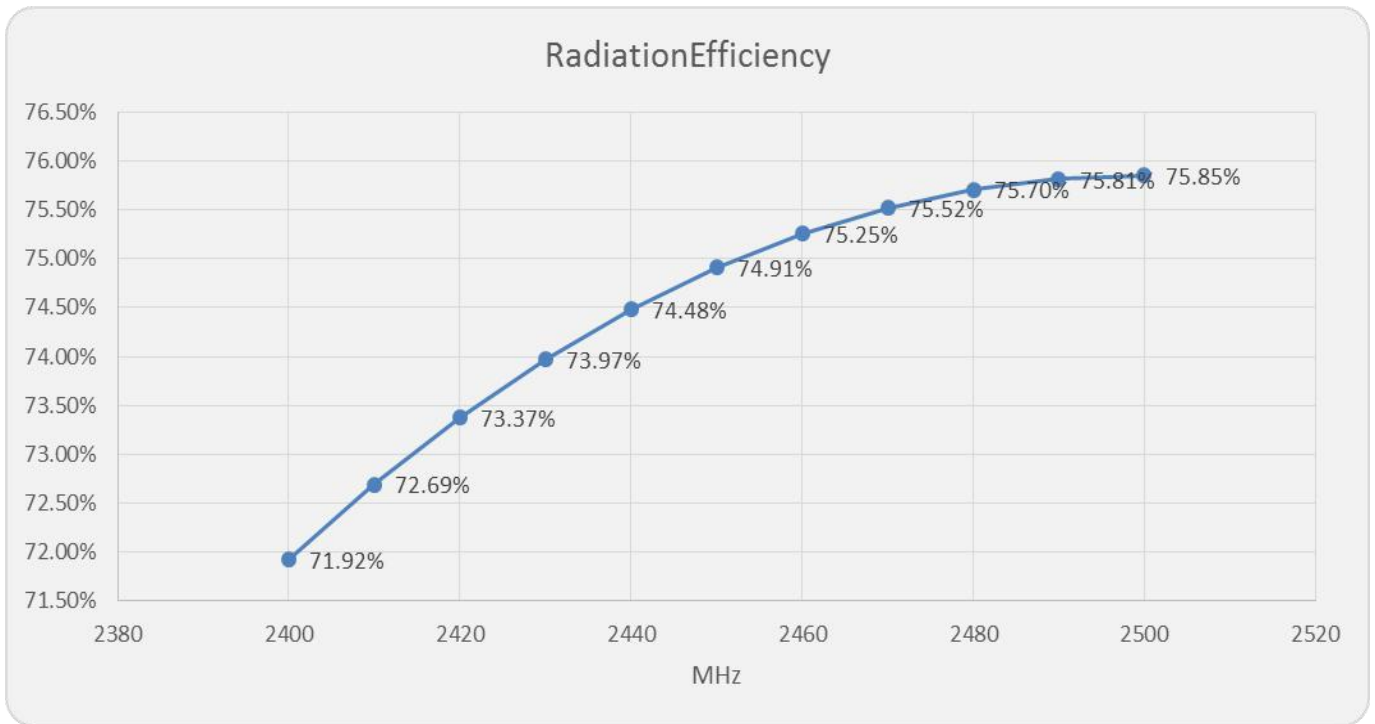
- **Radiation Pattern**

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

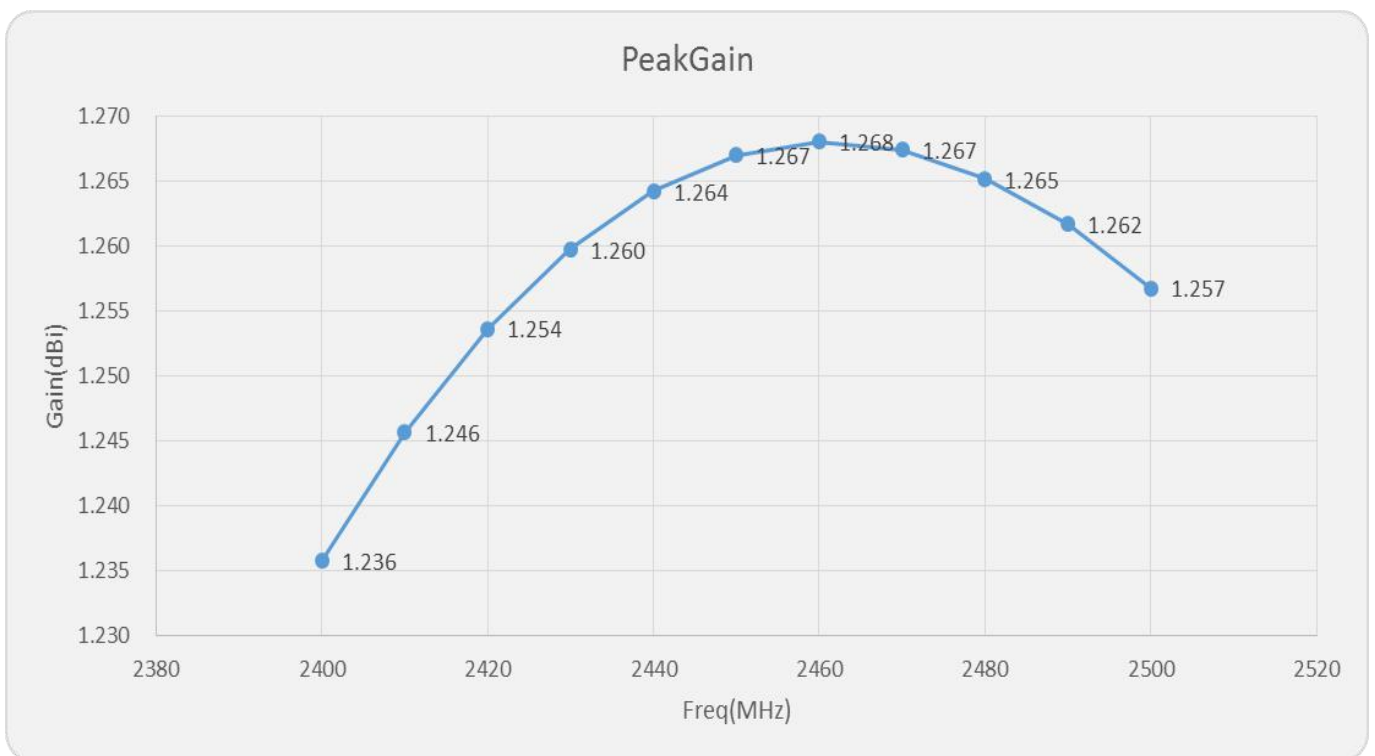



UNLESS OTHER SPECIFIED TOLERANCES ON: $0 = \pm 1$ $0.0 = \pm 0.50$ $0.00 = \pm 0.20$ ANGLES = \pm HOLE DIA = \pm		 Semitel Electronics Co.,Ltd	
SCALE: N/A DRAWN BY: SARA DESIGNED BY: HEXIN	UNIT: mm CHECKED BY: XD APPROVED BY: XD	THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION	
TITLE: SC2450P3216A0 Engineering Specification		DOCUMENT NO.	SC2450P3216B0
			SPEC REV. B0
		PAGE5	OF 9

● **Efficiency**

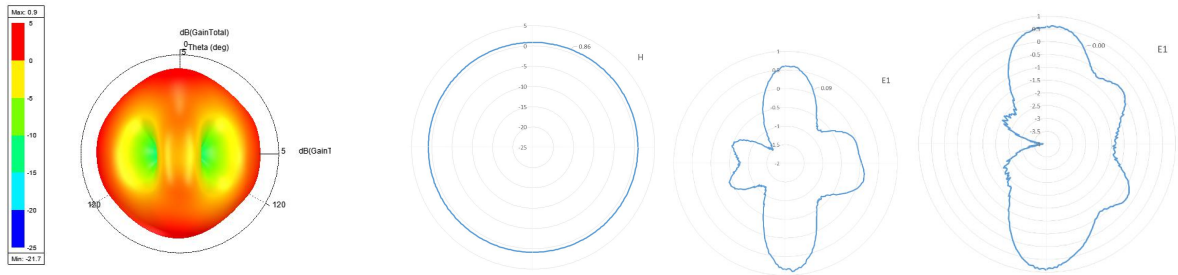


● **Peak Gain**

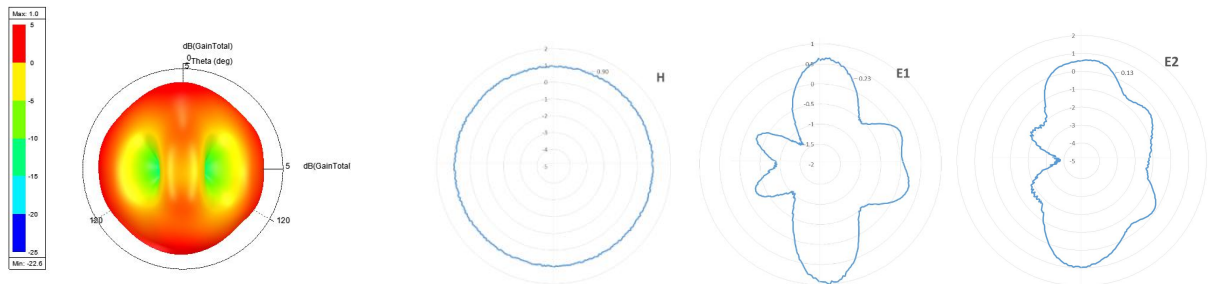


UNLESS OTHER SPECIFIED TOLERANCES ON: $0 = \pm 1$ $0.0 = \pm 0.50$ $0.00 = \pm 0.20$ ANGLES = \pm HOLE DIA = \pm		 Semitel Electronics Co.,Ltd	
SCALE: N/A DRAWN BY: SARA DESIGNED BY: HEXIN	UNIT: mm CHECKED BY: XD APPROVED BY: XD		THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION
TITLE: SC2450P3216A0 Engineering Specification		DOCUMENT NO. SC2450P3216B0	SPEC REV. B0
		PAGE 6	OF 9

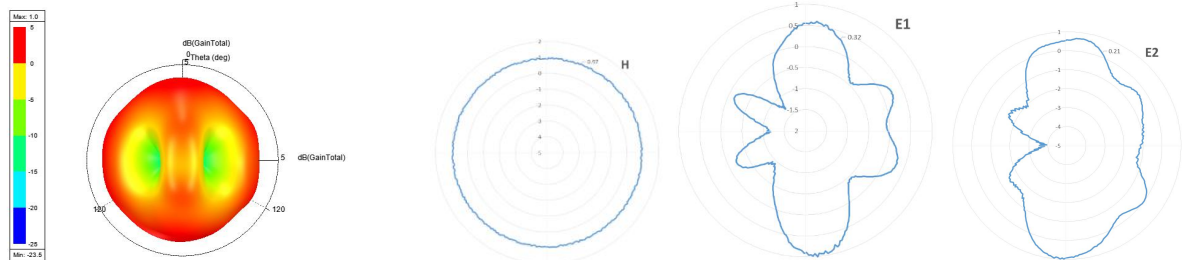
● 3D Gain Pattern (2400 MHz)




● 3D Gain Pattern (2440 MHz)



● 3D Gain Pattern (2480 MHz)



UNLESS OTHER SPECIFIED TOLERANCES ON: $0 = \pm 1$ $0.0 = \pm 0.50$ $0.00 = \pm 0.20$ ANGLES = \pm HOLE DIA = \pm		 Semitel Electronics Co.,Ltd	
SCALE: N/A DRAWN BY: SARA DESIGNED BY: HEXIN	UNIT: mm CHECKED BY: XD APPROVED BY: XD	THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION	
TITLE: SC2450P3216A0 Engineering Specification		DOCUMENT NO.	SC2450P3216B0
		PAGE 7	OF 9
			SPEC REV. B0

8.Environmental Characteristics

8.1 Reliability Test

Item	Condition	Specification
Thermal shock	1. 30±3 minutes at -40° C±5° C, 2. Convert to +105° C (5 minutes) 3. 30±3 minutes at +105° C±5° C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5° C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5°C 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245±5°C for 3±1 seconds.	No apparent damage

8.2 Storage Condition

(1) At warehouse:

The temperature should be within 0 ~ 30°C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(2) On board:

The temperature should be within

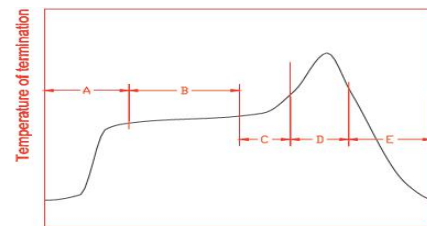
-40~85°C and humidity should be less than

85%RH.

8.3 Operating Temperature

Range

Operating temperature range : -40°C to +105°C.



	Time		
A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

UNLESS OTHER SPECIFIED TOLERANCES ON:

0=±1 0.0=±0.50 0.00=±0.20

ANGLES = ± HOLE DIA = ±



Semitel Electronics Co.,Ltd

SCALE: N/A

UNIT: mm

DRAWN BY: SARA

CHECKED BY: XD

DESIGNED BY: HEXIN

APPROVED BY: XD

THIS DRAWINGS AND SPECIFICATIONS ARE THEPROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION

TITLE: SC2450P3216A0Engineering Specification

DOCUMENT NO.

SC2450P3216B0

SPEC REV.

B0

PAGE8

OF

9

9. Recommended Reflow Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for all waves and re-flow soldering system. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

(a) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30 W.

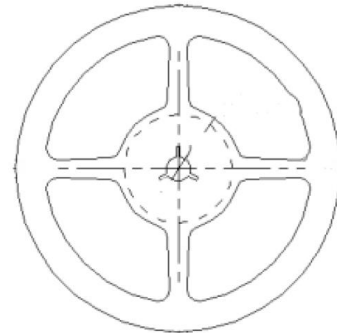
(b) The soldering gun tip shall not touch this product directly.


(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

10. Taping Package and Label marking: (unit: mm)

(1) Quantity/Reel: 5000pcs/Reel



UNLESS OTHER SPECIFIED TOLERANCES ON: $0 = \pm 1$ $0.0 = \pm 0.50$ $0.00 = \pm 0.20$ ANGLES = \pm HOLE DIA = \pm		 Semitel Electronics Co.,Ltd <small>Enabling your idea</small>		
SCALE: N/A	UNIT: mm	THIS DRAWINGS AND SPECIFICATIONS ARE THEPROPERTY OF SEMITELELECTRONICS Co.,Ltd. AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION		
DRAWN BY: SARA	CHECKED BY:XD			
DESIGNED BY: HEXIN	APPROVED BY: XD			
TITLE: SC2450P3216A0Engineering Specification		DOCUMENT NO.	SC2450P3216B0	SPEC REV.
				B0
		PAGE9		OF 9